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## What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

## Applications of "[Embedded - Microcontrollers](#)"

### Details

Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I <sup>2</sup> C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	87
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/m306n4mgt-168fpufq">https://www.e-xfl.com/product-detail/renesas-electronics-america/m306n4mgt-168fpufq</a>

**Table 1.3 List of Pin Names (1)**

Pin No.	Control	Port	Interrupt	Timer Pin	UART Pin	Analog	CAN Module	Bus Control Pin
FP	GP	Pin	Pin			Pin	Pin	
1	99		P9_6			ANEX1	CTX0	
2	100		P9_5			ANEX0	CRX0	
3	1		P9_4	TB4IN		DA1		
4	2		P9_3	TB3IN		DA0		
5	3		P9_2	TB2IN	SOUT3			
6	4		P9_1	TB1IN	SIN3			
7	5		P9_0	TB0IN	CLK3			
8	6	BYTE						
9	7	CNVSS						
10	8	XCIN	P8_7					
11	9	XCOUT	P8_6					
12	10	RESET						
13	11	XOUT						
14	12	VSS						
15	13	XIN						
16	14	VCC1						
17	15		P8_5	NMI				
18	16		P8_4	INT2	ZP			
19	17		P8_3	INT1				
20	18		P8_2	INT0				
21	19		P8_1	TA4IN/U				
22	20		P8_0	TA4OUT/U				
23	21		P7_7	TA3IN			CRX1	
24	22		P7_6	TA3OUT			CTX1	
25	23		P7_5	TA2IN/W				
26	24		P7_4	TA2OUT/W				
27	25		P7_3	TA1IN/V	CTS2/RTS2			
28	26		P7_2	TA1OUT/V	CLK2			
29	27		P7_1	TA0IN/TB5IN	RXD2/SCL2			
30	28		P7_0	TA0OUT	TXD2/SDA2			
31	29		P6_7		TXD1/SDA1			
32	30		P6_6		RXD1/SCL1			
33	31		P6_5		CLK1			
34	32		P6_4		CTS1/RTS1/CTS0/CLKS1			
35	33		P6_3		TXD0/SDA0			
36	34		P6_2		RXD0/SCL0			
37	35		P6_1		CLK0			
38	36		P6_0		CTS0/RTS0			
39	37		P5_7					RDY/CLKOUT
40	38		P5_6					ALE
41	39		P5_5					HOLD
42	40		P5_4					HLDA
43	41		P5_3					BCLK
44	42		P5_2					RD
45	43		P5_1					WRH/BHE
46	44		P5_0					WRL/WR
47	45		P4_7					CS3
48	46		P4_6					CS2
49	47		P4_5					CS1
50	48		P4_4					CS0

FP: PRQP0100JB-A (100P6S-A), GP: PLQP0100KB-A (100P6Q-A)

## 1.6 Pin Functions

Tables 1.5 to 1.7 list the Pin Functions.

**Table 1.5 Pin Functions (1)**

Signal Name	Pin Name	I/O Type	Description
Power supply input	VCC1, VCC2, VSS	I	Apply 4.2 to 5.5 V (T/V-ver.), 3.0 to 5.5 V (Normal-ver.) to the VCC1 and VCC2 pins and 0 V to the VSS pin. The VCC apply condition is that $VCC2 = VCC1^{(1)}$ .
Analog power supply input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect the AVCC pin to VCC1. Connect the AVSS pin to VSS.
Reset input	RESET	I	The MCU is in a reset state when applying "L" to the this pin.
CNVSS	CNVSS	I	Switches processor mode. Connect this pin to VSS to when after a reset to start up in single-chip mode. Connect this pin to VCC1 to start up in microprocessor mode.
External data bus width select input	BYTE	I	Switches the data bus in external memory space. The data bus is 16-bit long when the this pin is held "L" and 8-bit long when the this pin is held "H". Set it to either one. Connect this pin to VSS when single-chip mode.
Bus control pins	D0 to D7	I/O	Inputs and outputs data (D0 to D7) when these pins are set as the separate bus.
	D8 to D15	I/O	Inputs and outputs data (D8 to D15) when external 16-bit data bus is set as the separate bus.
	A0 to A19	O	Output address bits (A0 to A19).
	A0/D0 to A7/D7	I/O	Input and output data (D0 to D7) and output address bits (A0 to A7) by time-sharing when external 8-bit data bus are set as the multiplexed bus.
	A1/D0 to A8/D7	I/O	Input and output data (D0 to D7) and output address bits (A1 to A8) by time-sharing when external 16-bit data bus are set as the multiplexed bus.
	CS0 to CS3	O	Output CS0 to CS3 signals. CS0 to CS3 are chip-select signals to specify an external space.
	WRL/WR WRH/BHE RD	O	Output WRL, WRH, (WR, BHE), RD signals. WRL and WRH or BHE, and WR can be switched by program. <ul style="list-style-type: none"> <li>• WRL, WRH, and RD are selected The WRL signal becomes "L" by writing data to an even address in an external memory space. The WRH signal becomes "L" by writing data to an odd address in an external memory space. The RD pin signal becomes "L" by reading data in an external memory space.</li> <li>• WR, BHE, and RD are selected The WR signal becomes "L" by writing data in an external memory space. The RD signal becomes "L" by reading data in an external memory space. The BHE signal becomes "L" by accessing an odd address. Select WR, BHE, and RD for an external 8-bit data bus.</li> </ul>
	ALE	O	ALE is a signal to latch the address.
	HOLD	I	While the HOLD pin is held "L", the MCU is placed in a hold state.
	HLDA	O	In a hold state, HLDA outputs a "L" signal.
	RDY	I	While applying a "L" signal to the RDY pin, the MCU is placed in a wait state.

I: Input      O: Output      I/O: Input/Output

**NOTE:**

1. In this manual, hereafter, VCC refers to VCC1 unless otherwise noted.

### 2.3 Frame Base Register (FB)

FB is configured with 16 bits, and is used for FB relative addressing.

### 2.4 Interrupt Table Register (INTB)

INTB is configured with 20 bits, indicating the start address of an interrupt vector table.

### 2.5 Program Counter (PC)

PC is configured with 20 bits, indicating the address of an instruction to be executed.

### 2.6 User Stack Pointer (USP), Interrupt Stack Pointer (ISP)

Stack pointer (SP) comes in two types: USP and ISP, each configured with 16 bits.

Your desired type of stack pointer (USP or ISP) can be selected by the U flag of FLG.

### 2.7 Static Base Register (SB)

SB is configured with 16 bits, and is used for SB relative addressing.

### 2.8 Flag Register (FLG)

FLG consists of 11 bits, indicating the CPU status.

#### 2.8.1 Carry Flag (C Flag)

This flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic/logic unit.

#### 2.8.2 Debug Flag (D Flag)

This flag is used exclusively for debugging purpose. During normal use, set to 0.

#### 2.8.3 Zero Flag (Z Flag)

This flag is set to 1 when an arithmetic operation resulted in 0; otherwise, it is 0.

#### 2.8.4 Sign Flag (S Flag)

This flag is set to 1 when an arithmetic operation resulted in a negative value; otherwise, it is 0.

#### 2.8.5 Register Bank Select Flag (B Flag)

Register bank 0 is selected when this flag is 0; register bank 1 is selected when this flag is 1.

#### 2.8.6 Overflow Flag (O Flag)

This flag is set to 1 when the operation resulted in an overflow; otherwise, it is 0.

#### 2.8.7 Interrupt Enable Flag (I Flag)

This flag enables a maskable interrupt.

Maskable interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when the interrupt request is accepted.

#### 2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is 0; USP is selected when the U flag is 1.

The U flag is set to 0 when a hardware interrupt request is accepted or an INT instruction for software interrupt Nos. 0 to 31 is executed.

#### 2.8.9 Processor Interrupt Priority Level (IPL)

IPL is configured with three bits, for specification of up to eight processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has priority greater than IPL, the interrupt request is enabled.

#### 2.8.10 Reserved Area

When write to this bit, write 0. When read, its content is undefined.

Table 4.9 SFR Information (9)

Address	Register	Symbol	After Reset
0200h	CAN0 Message Control Register 0	C0MCTL0	00h
0201h	CAN0 Message Control Register 1	C0MCTL1	00h
0202h	CAN0 Message Control Register 2	C0MCTL2	00h
0203h	CAN0 Message Control Register 3	C0MCTL3	00h
0204h	CAN0 Message Control Register 4	C0MCTL4	00h
0205h	CAN0 Message Control Register 5	C0MCTL5	00h
0206h	CAN0 Message Control Register 6	C0MCTL6	00h
0207h	CAN0 Message Control Register 7	C0MCTL7	00h
0208h	CAN0 Message Control Register 8	C0MCTL8	00h
0209h	CAN0 Message Control Register 9	C0MCTL9	00h
020Ah	CAN0 Message Control Register 10	C0MCTL10	00h
020Bh	CAN0 Message Control Register 11	C0MCTL11	00h
020Ch	CAN0 Message Control Register 12	C0MCTL12	00h
020Dh	CAN0 Message Control Register 13	C0MCTL13	00h
020Eh	CAN0 Message Control Register 14	C0MCTL14	00h
020Fh	CAN0 Message Control Register 15	C0MCTL15	00h
0210h	CAN0 Control Register	C0CTLR	X0000001b
0211h			XX0X0000b
0212h	CAN0 Status Register	C0STR	00h
0213h			X0000001b
0214h	CAN0 Slot Status Register	C0SSTR	00h
0215h			00h
0216h	CAN0 Interrupt Control Register	C0ICR	00h
0217h			00h
0218h	CAN0 Extended ID Register	C0IDR	00h
0219h			00h
021Ah	CAN0 Configuration Register	C0CONR	XXh
021Bh			XXh
021Ch	CAN0 Receive Error Count Register	C0RECR	00h
021Dh	CAN0 Transmit Error Count Register	C0TECR	00h
021Eh	CAN0 Time Stamp Register	C0TSR	00h
021Fh			00h
0220h	CAN1 Message Control Register 0	C1MCTL0	00h
0221h	CAN1 Message Control Register 1	C1MCTL1	00h
0222h	CAN1 Message Control Register 2	C1MCTL2	00h
0223h	CAN1 Message Control Register 3	C1MCTL3	00h
0224h	CAN1 Message Control Register 4	C1MCTL4	00h
0225h	CAN1 Message Control Register 5	C1MCTL5	00h
0226h	CAN1 Message Control Register 6	C1MCTL6	00h
0227h	CAN1 Message Control Register 7	C1MCTL7	00h
0228h	CAN1 Message Control Register 8	C1MCTL8	00h
0229h	CAN1 Message Control Register 9	C1MCTL9	00h
022Ah	CAN1 Message Control Register 10	C1MCTL10	00h
022Bh	CAN1 Message Control Register 11	C1MCTL11	00h
022Ch	CAN1 Message Control Register 12	C1MCTL12	00h
022Dh	CAN1 Message Control Register 13	C1MCTL13	00h
022Eh	CAN1 Message Control Register 14	C1MCTL14	00h
022Fh	CAN1 Message Control Register 15	C1MCTL15	00h
0230h	CAN1 Control Register	C1CTLR	X0000001b
0231h			XX0X0000b
0232h	CAN1 Status Register	C1STR	00h
0233h			X0000001b
0234h	CAN1 Slot Status Register	C1SSTR	00h
0235h			00h
0236h	CAN1 Interrupt Control Register	C1ICR	00h
0237h			00h
0238h	CAN1 Extended ID Register	C1IDR	00h
0239h			00h
023Ah	CAN1 Configuration Register	C1CONR	XXh
023Bh			XXh
023Ch	CAN1 Receive Error Count Register	C1RECR	00h
023Dh	CAN1 Transmit Error Count Register	C1TECR	00h
023Eh	CAN1 Time Stamp Register	C1TSR	00h
023Fh			00h

X: Undefined

**Table 4.10 SFR Information (10)** <sup>(1)</sup>

Address	Register	Symbol	After Reset
0240h			
0241h			
0242h	CAN0 Acceptance Filter Support Register	C0AFS	XXh
0243h			XXh
0244h	CAN1 Acceptance Filter Support Register	C1AFS	XXh
0245h			XXh
0246h			
0247h			
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh	Peripheral Clock Select Register	PCLKR	00h
025Fh	CAN0/1 Clock Select Register	CCLKR	00h
0260h	CAN1 Message Box 0: Identifier / DLC		XXh
0261h			XXh
0262h			XXh
0263h			XXh
0264h			XXh
0265h			XXh
0266h	CAN1 Message Box 0: Data Field		XXh
0267h			XXh
0268h			XXh
0269h			XXh
026Ah			XXh
026Bh			XXh
026Ch	CAN1 Message Box 0:Time Stamp		XXh
026Dh			XXh
026Eh	CAN1 Message Box 1: Identifier / DLC		XXh
026Fh			XXh
0270h			XXh
0271h			XXh
0272h			XXh
0273h			XXh
0274h	CAN1 Message Box 1: Data Field		XXh
0275h			XXh
0276h			XXh
0277h			XXh
0278h			XXh
0279h			XXh
027Ah	CAN1 Message Box 1:Time Stamp		XXh
027Bh			XXh
027Ch			
027Dh			
027Eh			
027Fh			

X: Undefined

## NOTE:

- Blank spaces are reserved. No access is allowed.

**Table 4.11 SFR Information (11)**

Address	Register	Symbol	After Reset
0280h	CAN1 Message Box 2: Identifier / DLC		XXh
0281h			XXh
0282h			XXh
0283h			XXh
0284h			XXh
0285h			XXh
0286h	CAN1 Message Box 2: Data Field		XXh
0287h			XXh
0288h			XXh
0289h			XXh
028Ah			XXh
028Bh			XXh
028Ch			XXh
028Dh			XXh
028Eh	CAN1 Message Box 2: Time Stamp		XXh
028Fh			XXh
0290h	CAN1 Message Box 3: Identifier / DLC		XXh
0291h			XXh
0292h			XXh
0293h			XXh
0294h			XXh
0295h			XXh
0296h	CAN1 Message Box 3: Data Field		XXh
0297h			XXh
0298h			XXh
0299h			XXh
029Ah			XXh
029Bh			XXh
029Ch			XXh
029Dh			XXh
029Eh	CAN1 Message Box 3: Time Stamp		XXh
029Fh			XXh
02A0h	CAN1 Message Box 4: Identifier / DLC		XXh
02A1h			XXh
02A2h			XXh
02A3h			XXh
02A4h			XXh
02A5h			XXh
02A6h	CAN1 Message Box 4: Data Field		XXh
02A7h			XXh
02A8h			XXh
02A9h			XXh
02AAh			XXh
02ABh			XXh
02ACh			XXh
02ADh			XXh
02AEh	CAN1 Message Box 4: Time Stamp		XXh
02AFh			XXh
02B0h	CAN1 Message Box 5: Identifier / DLC		XXh
02B1h			XXh
02B2h			XXh
02B3h			XXh
02B4h			XXh
02B5h			XXh
02B6h	CAN1 Message Box 5: Data Field		XXh
02B7h			XXh
02B8h			XXh
02B9h			XXh
02BAh			XXh
02BBh			XXh
02BCh			XXh
02BDh			XXh
02BEh	CAN1 Message Box 5: Time Stamp		XXh
02BFh			XXh

X: Undefined

**Table 4.13 SFR Information (13)**

Address	Register	Symbol	After Reset
0300h	CAN1 Message Box 10: Identifier / DLC		XXh
0301h			XXh
0302h			XXh
0303h			XXh
0304h			XXh
0305h	CAN1 Message Box 10: Data Field		XXh
0306h			XXh
0307h			XXh
0308h			XXh
0309h			XXh
030Ah			XXh
030Bh			XXh
030Ch	CAN1 Message Box 10: Time Stamp		XXh
030Dh			XXh
030Eh	CAN1 Message Box 11: Identifier / DLC		XXh
030Fh			XXh
0310h			XXh
0311h			XXh
0312h			XXh
0313h	CAN1 Message Box 11: Data Field		XXh
0314h			XXh
0315h			XXh
0316h			XXh
0317h			XXh
0318h			XXh
0319h			XXh
031Ah	CAN1 Message Box 11: Time Stamp		XXh
031Bh			XXh
031Ch	CAN1 Message Box 12: Identifier / DLC		XXh
031Dh			XXh
031Eh			XXh
031Fh			XXh
0320h			XXh
0321h	CAN1 Message Box 12: Data Field		XXh
0322h			XXh
0323h			XXh
0324h			XXh
0325h			XXh
0326h			XXh
0327h			XXh
0328h	CAN1 Message Box 12: Time Stamp		XXh
0329h			XXh
032Ah	CAN1 Message Box 13: Identifier / DLC		XXh
032Bh			XXh
032Ch			XXh
032Dh			XXh
032Eh			XXh
032Fh	CAN1 Message Box 13: Data Field		XXh
0330h			XXh
0331h			XXh
0332h			XXh
0333h			XXh
0334h			XXh
0335h			XXh
0336h	CAN1 Message Box 13: Time Stamp		XXh
0337h			XXh
0338h	CAN1 Message Box 13: Data Field		XXh
0339h			XXh
033Ah			XXh
033Bh			XXh
033Ch			XXh
033Dh	CAN1 Message Box 13: Time Stamp		XXh
033Eh			XXh
033Fh			XXh

X: Undefined



**Timing Requirements****VCC = 5 V****(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)****Table 5.11 Timer A Input (Counter Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c(TA)</sub>	TAiIN input cycle time	100		ns
t <sub>w(TAH)</sub>	TAiIN input HIGH pulse width	40		ns
t <sub>w(TAL)</sub>	TAiIN input LOW pulse width	40		ns

**Table 5.12 Timer A Input (Gating Input in Timer Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c(TA)</sub>	TAiIN input cycle time	400		ns
t <sub>w(TAH)</sub>	TAiIN input HIGH pulse width	200		ns
t <sub>w(TAL)</sub>	TAiIN input LOW pulse width	200		ns

**Table 5.13 Timer A Input (External Trigger Input in One-shot Timer Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c(TA)</sub>	TAiIN input cycle time	200		ns
t <sub>w(TAH)</sub>	TAiIN input HIGH pulse width	100		ns
t <sub>w(TAL)</sub>	TAiIN input LOW pulse width	100		ns

**Table 5.14 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>w(TAH)</sub>	TAiIN input HIGH pulse width	100		ns
t <sub>w(TAL)</sub>	TAiIN input LOW pulse width	100		ns

**Table 5.15 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)**

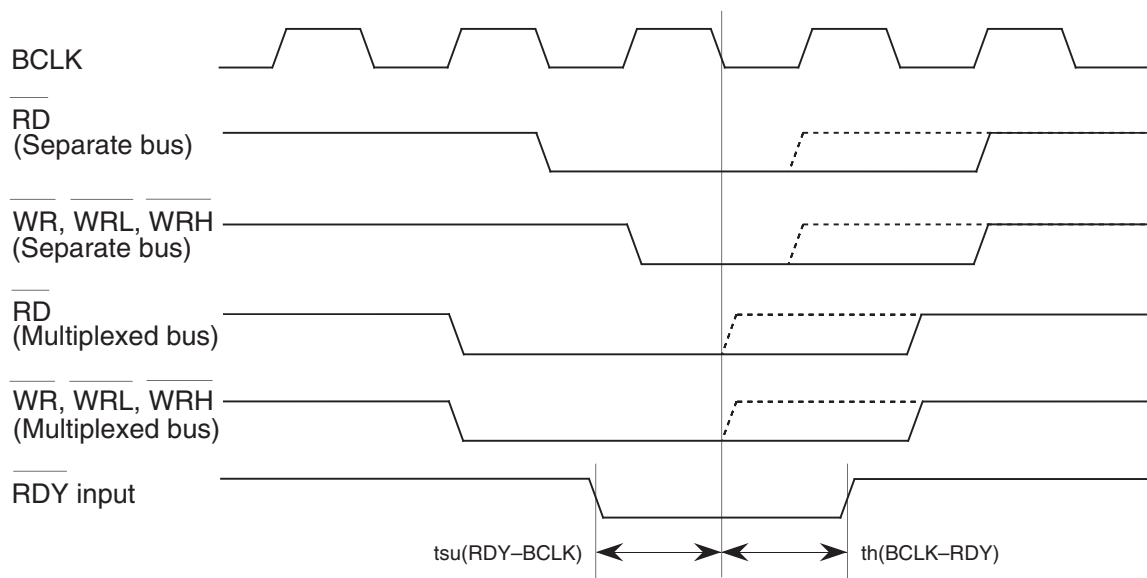
Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c(UP)</sub>	TAiOUT input cycle time	2000		ns
t <sub>w(UPH)</sub>	TAiOUT input HIGH pulse width	1000		ns
t <sub>w(UPL)</sub>	TAiOUT input LOW pulse width	1000		ns
t <sub>su(UP-TIN)</sub>	TAiOUT input setup time	400		ns
t <sub>h(TIN-UP)</sub>	TAiOUT input hold time	400		ns

**Table 5.16 Timer A Input (Two-phase Pulse Input in Event Counter Mode)**

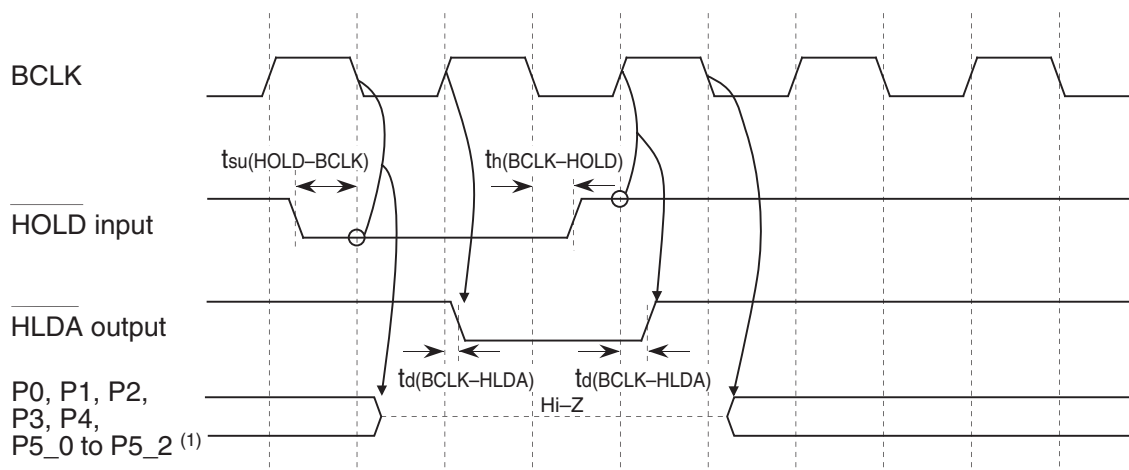
Symbol	Parameter	Standard		Unit
		Min.	Max.	
t <sub>c(TA)</sub>	TAiIN input cycle time	800		ns
t <sub>su(TAIN-TAOUT)</sub>	TAiOUT input setup time	200		ns
t <sub>su(TAOUT-TAIN)</sub>	TAiIN input setup time	200		ns

**Memory Expansion Mode and Microprocessor Mode****VCC = 5 V**

(Effective for setting with wait)



(Common to setting with wait and setting without wait)

**NOTE:**

1. The above pins are set to high-impedance regardless of the input level of the BYTE pin, the PM06 bit in the PM0 register, and the PM11 bit in the PM1 register.

**Measuring conditions :**

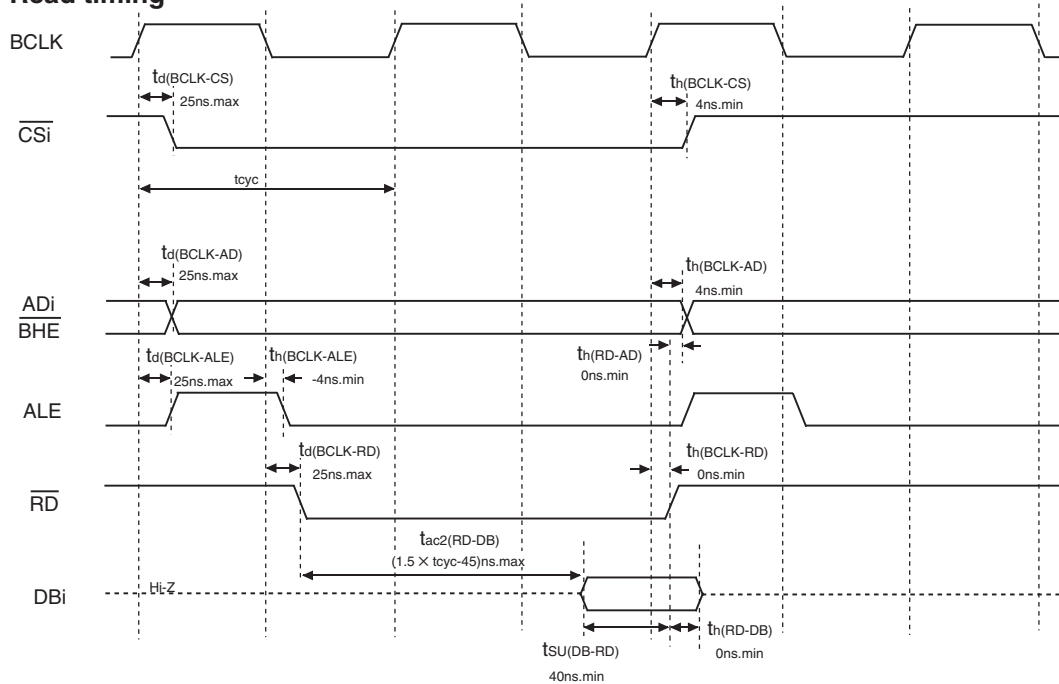
- VCC = 5 V
- Input timing voltage : Determined with  $V_{IL} = 1.0 \text{ V}$ ,  $V_{IH} = 4.0 \text{ V}$
- Output timing voltage: Determined with  $V_{OL} = 2.5 \text{ V}$ ,  $V_{OH} = 2.5 \text{ V}$

**Figure 5.4 Timing Diagram (2)**

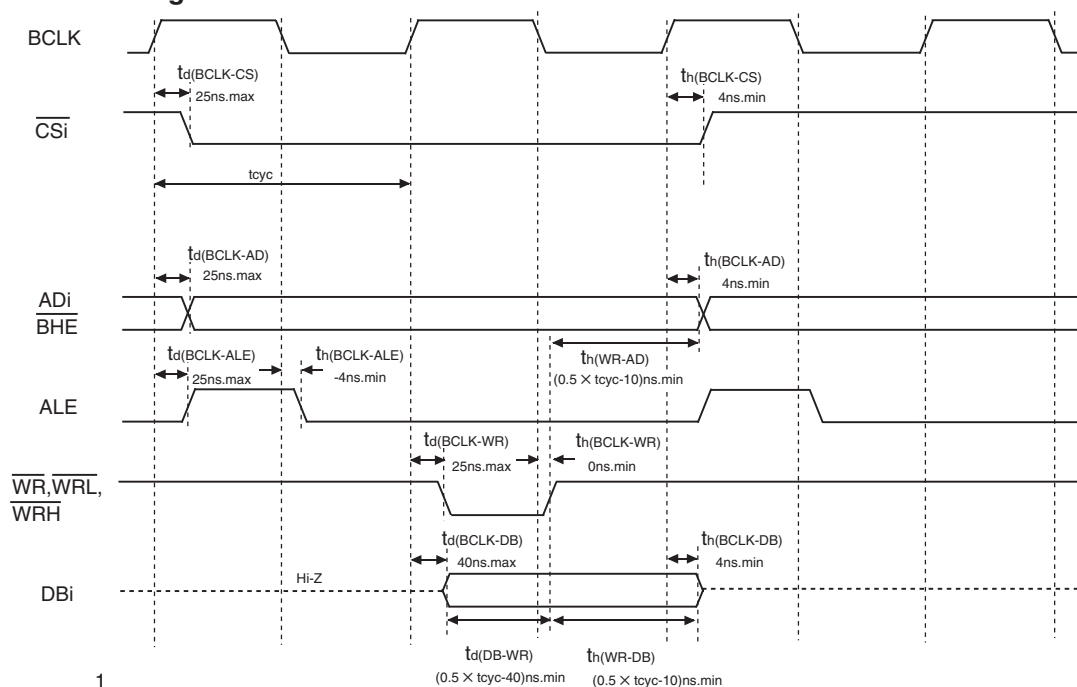
## Memory Expansion Mode and Microprocessor Mode (For 1-wait setting and external area access)

VCC = 5 V

### Read timing



### Write timing



$$t_{\text{cyc}} = \frac{1}{f(\text{BCLK})}$$

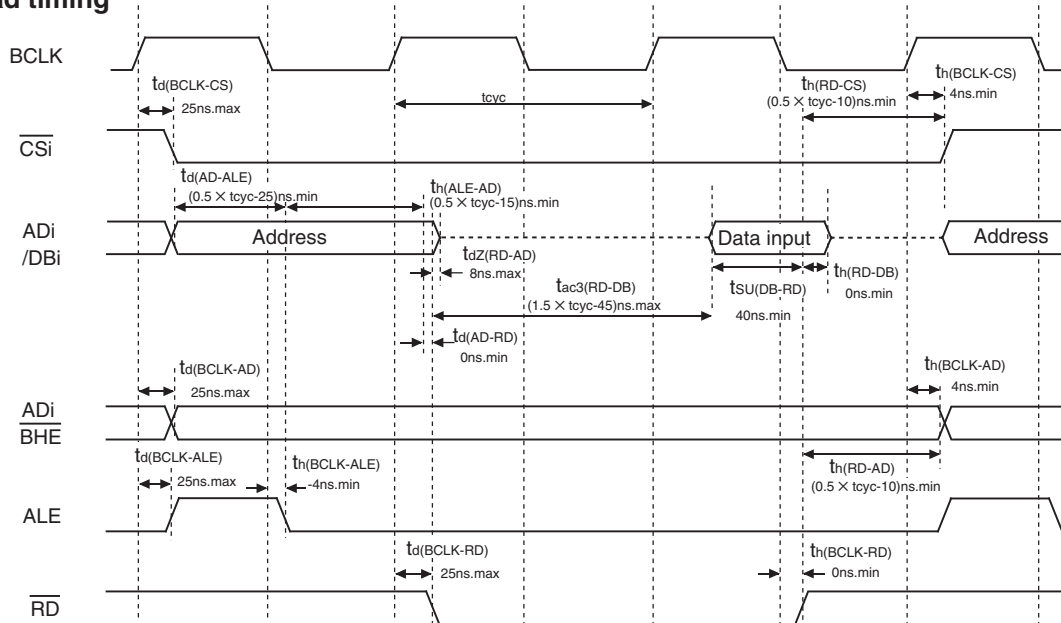
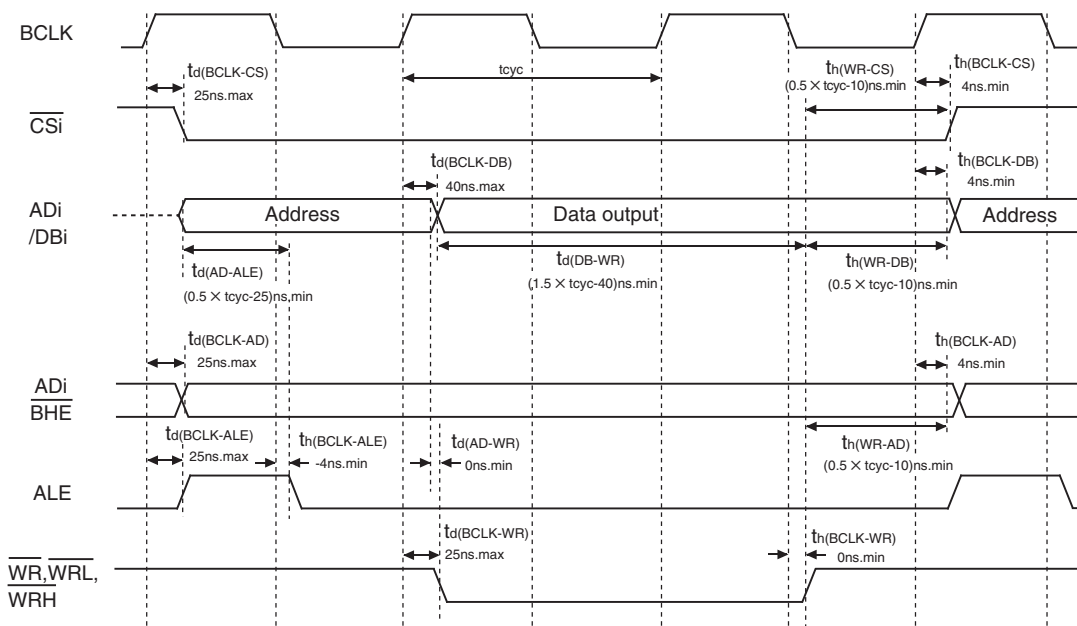
Measuring conditions :

- VCC = 5 V
- Input timing voltage :  $V_{\text{IL}} = 0.8 \text{ V}$ ,  $V_{\text{IH}} = 2.0 \text{ V}$
- Output timing voltage :  $V_{\text{OL}} = 0.4 \text{ V}$ ,  $V_{\text{OH}} = 2.4 \text{ V}$

Figure 5.6 Timing Diagram (4)

**Memory Expansion Mode and Microprocessor Mode****VCC = 5 V**

(For 1- or 2-wait setting, external area access and multiplexed bus selection)

**Read timing****Write timing**

$$t_{\text{cyc}} = \frac{1}{f(\text{BCLK})}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage :  $V_{\text{IL}} = 0.8 \text{ V}$ ,  $V_{\text{IH}} = 2.0 \text{ V}$
- Output timing voltage :  $V_{\text{OL}} = 0.4 \text{ V}$ ,  $V_{\text{OH}} = 2.4 \text{ V}$

**Figure 5.9 Timing Diagram (7)**

**Table 5.27 Recommended Operating Conditions (1) <sup>(1)</sup>**

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V <sub>CC</sub>	Supply voltage (VCC1 = VCC2)		3.0	5.0	5.5	V
AV <sub>CC</sub>	Analog supply voltage			V <sub>CC</sub>		V
V <sub>SS</sub>	Supply voltage			0		V
AV <sub>SS</sub>	Analog supply voltage			0		V
V <sub>IH</sub>	HIGH input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, XIN, RESET, CNVSS, BYTE	0.8 V <sub>CC</sub>		V <sub>CC</sub>	V
		P7_1, P9_1	0.8 V <sub>CC</sub>		6.5	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (During single-chip mode)	0.8 V <sub>CC</sub>		V <sub>CC</sub>	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (Data input during memory expansion and microprocessor modes)	0.5 V <sub>CC</sub>		V <sub>CC</sub>	V
V <sub>IL</sub>	LOW input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, RESET, CNVSS, BYTE	0		0.2 V <sub>CC</sub>	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (During single-chip mode)	0		0.2 V <sub>CC</sub>	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (Data input during memory expansion and microprocessor modes)	0		0.16 V <sub>CC</sub>	V
I <sub>OH(peak)</sub>	HIGH peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7			−10.0	mA
I <sub>OH(avg)</sub>	HIGH average output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7			−5.0	mA
I <sub>OL(peak)</sub>	LOW peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			10.0	mA
I <sub>OL(avg)</sub>	LOW average output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			5.0	mA

**NOTES:**

1. Referenced to VCC = 3.0 to 5.5 V at T<sub>opr</sub> = −40 to 85°C unless otherwise specified.
2. Average output current values during 100 ms period.
3. The total I<sub>OL(peak)</sub> for ports P0, P1, P2, P8\_6, P8\_7, P9, and P10 must be 80 mA max.  
The total I<sub>OL(peak)</sub> for ports P3, P4, P5, P6, P7, and P8\_0 to P8\_4 must be 80 mA max.  
The total I<sub>OH(peak)</sub> for ports P0, P1, and P2 must be −40 mA max.  
The total I<sub>OH(peak)</sub> for ports P3, P4, and P5 must be −40 mA max.  
The total I<sub>OH(peak)</sub> for ports P6, P7, and P8\_0 to P8\_4 must be −40 mA max.  
The total I<sub>OH(peak)</sub> for ports P8\_6, P8\_7, P9, and P10 must be −40 mA max.

**Switching Characteristics****VCC = 5 V****(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)****Table 5.48 Memory Expansion Mode and Microprocessor Mode (for setting with no wait)**

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.12		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		–4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) <sup>(3)</sup>		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) <sup>(3)</sup>		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	HLDA output delay time			40	ns

**NOTES:**

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 40 \text{ [ns]} \quad f(BCLK) \text{ is 12.5 MHz or less.}$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.

Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.

Hold time of data bus is expressed in

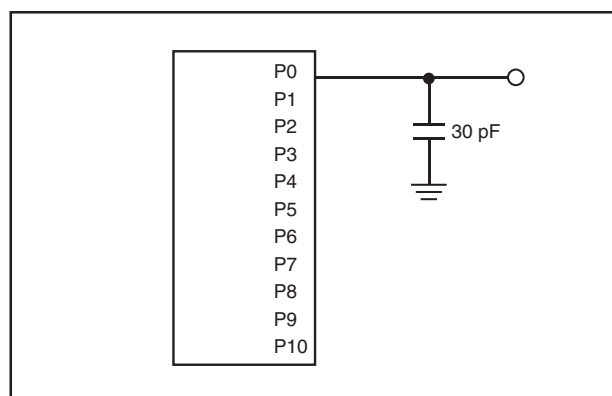
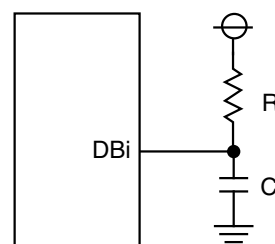
$$t = -CR \times \ln(1 - V_{OL} / V_{CC})$$

by a circuit of the right figure.

For example, when  $V_{OL} = 0.2 V_{CC}$ ,  $C = 30 \text{ pF}$ ,

$R = 1 \text{ k}\Omega$ , hold time of output “L” level is

$$t = -30 \text{ pF} \times 1 \text{ k}\Omega \times \ln(1 - 0.2 V_{CC} / V_{CC}) = 6.7 \text{ ns.}$$

**Figure 5.12 Port P0 to P10 Measurement Circuit**

**Switching Characteristics****VCC = 5 V****(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)****Table 5.49 Memory Expansion Mode and Microprocessor Mode (for 1- to 3-wait setting and external area access)**

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
t <sub>d</sub> (BCLK-AD)	Address output delay time	Figure 5.12		25	ns
t <sub>h</sub> (BCLK-AD)	Address output hold time (in relation to BCLK)		4		ns
t <sub>h</sub> (RD-AD)	Address output hold time (in relation to RD)		0		ns
t <sub>h</sub> (WR-AD)	Address output hold time (in relation to WR)		(NOTE 1)		ns
t <sub>d</sub> (BCLK-CS)	Chip select output delay time			25	ns
t <sub>h</sub> (BCLK-CS)	Chip select output hold time (in relation to BCLK)		4		ns
t <sub>d</sub> (BCLK-ALE)	ALE signal output delay time			15	ns
t <sub>h</sub> (BCLK-ALE)	ALE signal output hold time		–4		ns
t <sub>d</sub> (BCLK-RD)	RD signal output delay time			25	ns
t <sub>h</sub> (BCLK-RD)	RD signal output hold time		0		ns
t <sub>d</sub> (BCLK-WR)	WR signal output delay time			25	ns
t <sub>h</sub> (BCLK-WR)	WR signal output hold time		0		ns
t <sub>d</sub> (BCLK-DB)	Data output delay time (in relation to BCLK)			40	ns
t <sub>h</sub> (BCLK-DB)	Data output hold time (in relation to BCLK) <sup>(3)</sup>		4		ns
t <sub>d</sub> (DB-WR)	Data output delay time (in relation to WR)		(NOTE 2)		ns
t <sub>h</sub> (WR-DB)	Data output hold time (in relation to WR) <sup>(3)</sup>		(NOTE 1)		ns
t <sub>d</sub> (BCLK-HLDA)	HLDA output delay time			40	ns

**NOTES:**

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(\text{BCLK})} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(\text{BCLK})} - 40 \text{ [ns]}$$

n is “1” for 1-wait setting, “2” for 2-wait setting and “3” for 3-wait setting.  
When n = 1, f(BCLK) is 12.5 MHz or less.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.

Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.

Hold time of data bus is expressed in

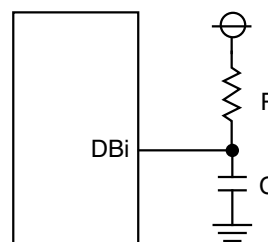
$$t = -CR \times \ln(1 - V_{OL} / V_{CC})$$

by a circuit of the right figure.

For example, when  $V_{OL} = 0.2 V_{CC}$ ,  $C = 30 \text{ pF}$ ,

$R = 1 \text{ k}\Omega$ , hold time of output “L” level is

$$t = -30 \text{ pF} \times 1 \text{ k}\Omega \times \ln(1 - 0.2 V_{CC} / V_{CC}) = 6.7 \text{ ns.}$$

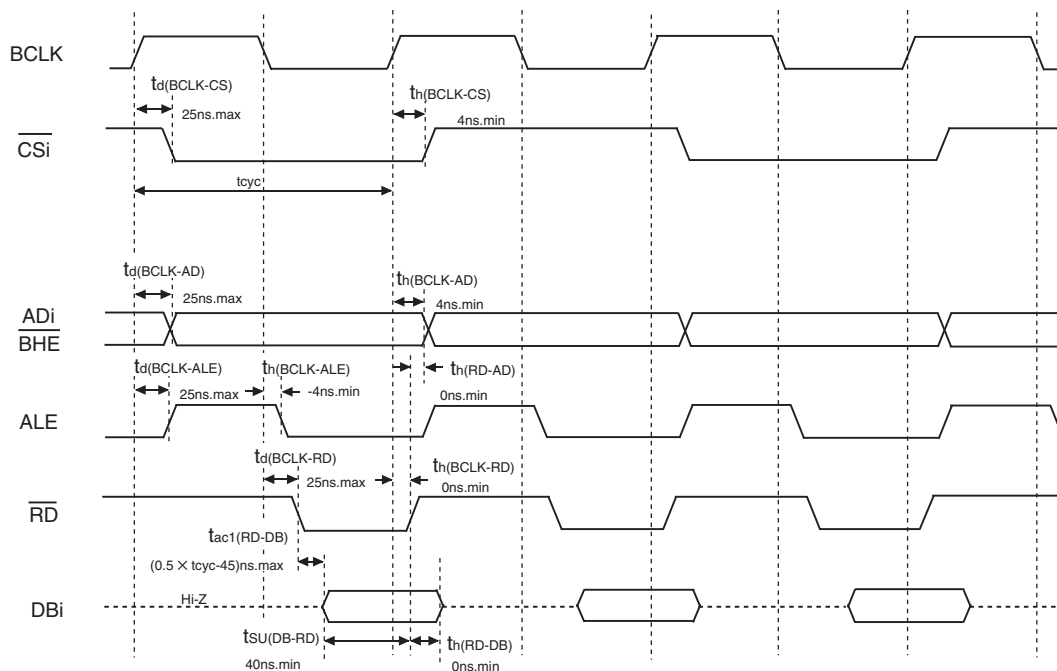


## Memory Expansion Mode and Microprocessor Mode

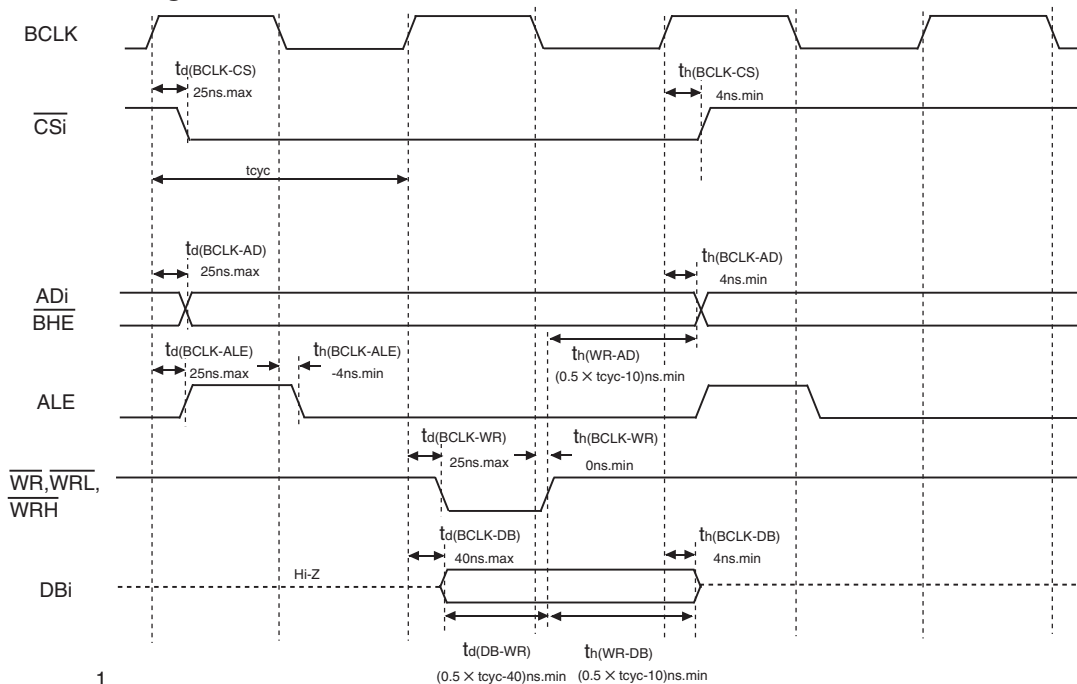
(For setting with no wait)

VCC = 5 V

### Read timing



### Write timing



$$t_{cyc} = \frac{1}{f(\text{BCLK})}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage :  $V_{IL} = 0.8 \text{ V}$ ,  $V_{IH} = 2.0 \text{ V}$
- Output timing voltage :  $V_{OL} = 0.4 \text{ V}$ ,  $V_{OH} = 2.4 \text{ V}$

Figure 5.15 Timing Diagram (3)



**Timing Requirements****VCC = 3.3 V****(Referenced to VCC = 3.3 V, VSS = 0 V, at Topr = -40 to 85°C unless otherwise specified)****Table 5.60 Timer B Input (Counter Input in Event Counter Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	150		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	60		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	60		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	300		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	120		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	120		ns

**Table 5.61 Timer B Input (Pulse Period Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	600		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	300		ns

**Table 5.62 Timer B Input (Pulse Width Measurement Mode)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	600		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	300		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	300		ns

**Table 5.63 A/D Trigger Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(AD)}$	ADTRG $\bar{}$ input cycle time (trigger able minimum)	1500		ns
$t_{w(ADL)}$	ADTRG $\bar{}$ input LOW pulse width	200		ns

**Table 5.64 Serial Interface**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	150		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	150		ns
$t_{d(C-Q)}$	TXDi output delay time		160	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	100		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

**Table 5.65 External Interrupt INTi Input**

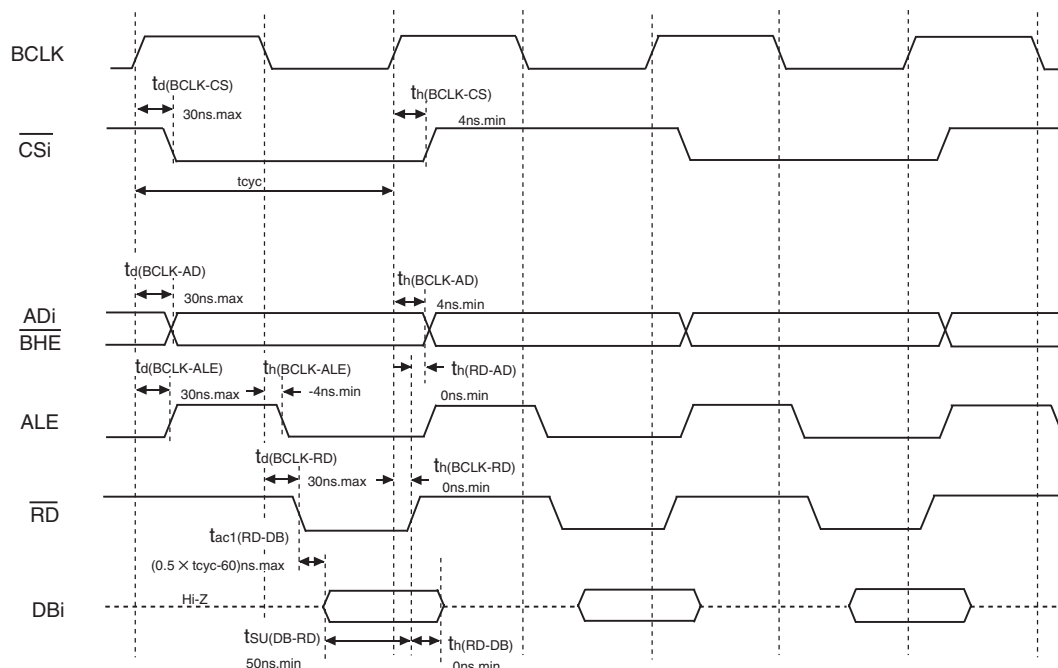
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	INTi input HIGH pulse width	380		ns
$t_{w(INL)}$	INTi input LOW pulse width	380		ns

## Memory Expansion Mode and Microprocessor Mode

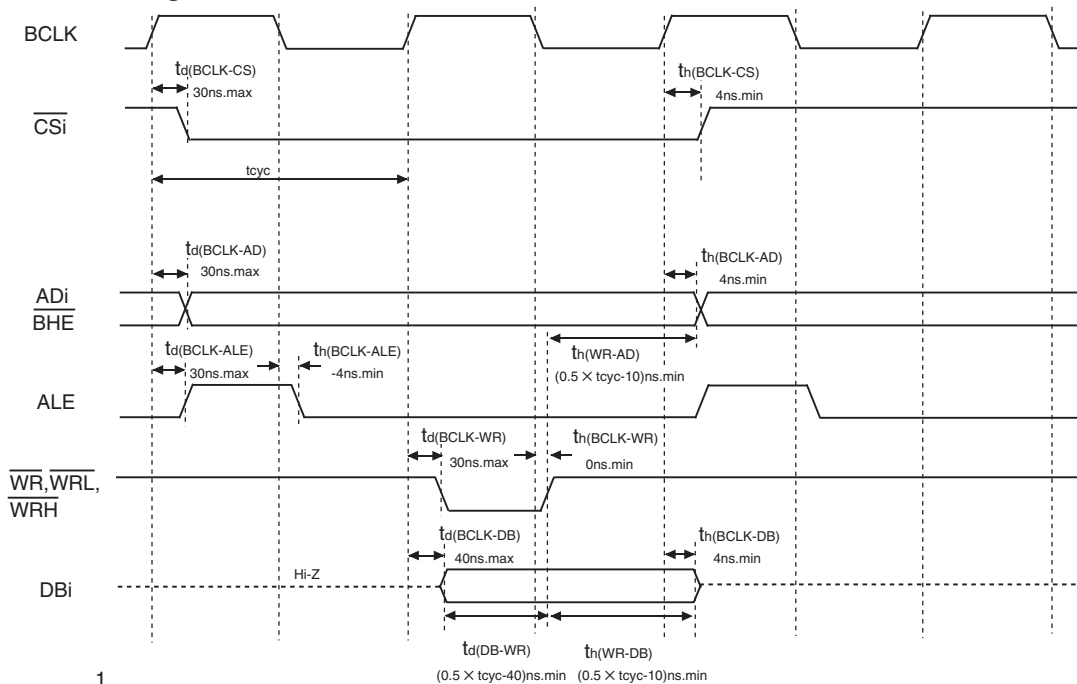
(For setting with no wait)

VCC = 3.3 V

### Read timing



### Write timing



$$t_{cyc} = \frac{1}{f(\text{BCLK})}$$

Measuring conditions :

- VCC = 3.3 V
- Input timing voltage :  $V_{IL} = 0.6 \text{ V}$ ,  $V_{IH} = 2.7 \text{ V}$
- Output timing voltage :  $V_{OL} = 1.65 \text{ V}$ ,  $V_{OH} = 1.65 \text{ V}$

Figure 5.24 Timing Diagram (3)

# REVISION HISTORY

# M16C/6N Group (M16C/6N4) Data Sheet

Rev.	Date	Description	
		Page	Summary
2.00	Nov. 10, 2004	34	Table 5.6 A/D Conversion Characteristics: "Tolerance Level Impedance" is added.
		35	Table 5.8 Power Supply Circuit Timing Characteristics: " $t_{d(M-L)}$ " is deleted. Figure 5.2 Power Supply Circuit Timing Diagram is added.
		36	Table 5.10 Memory Expansion Mode and Microprocessor Mode: " $t_{d(BCLK-HLDA)}$ " is deleted.
		38	Table 5.21 Serial I/O: Min. of standard in $t_{su(D-C)}$ is revised from "30" to "70".
		39	Table 5.23 Memory Expansion Mode and Microprocessor Mode (for setting with no wait) • Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15". • $t_{d(BCLK-HLDA)}$ is added.
		40	Table 5.24 Memory Expansion Mode and Microprocessor Mode (for 1- to 3-wait setting and external area access) • Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15". • $t_{d(BCLK-HLDA)}$ is added.
		41	Table 5.25 Memory Expansion Mode and Microprocessor Mode (for 2- to 3-wait setting, external area access and multiplexed bus selection) • $t_{d(BCLK-HLDA)}$ is added. • Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15".
		42	Figure 5.4 Timing Diagram (1): "XIN input" is added.
		44, 45	Figures 5.6 and 5.7 Timing Diagram (3) (4): "DB" in Read timing is revised to "DBi".
		46, 47	Figures 5.8 and 5.9 Timing Diagram (5) (6): "DB" in Write timing is revised to "DBi".
		49	Figure 5.11 Timing Diagram (8) • "ADi/DB" in Read/Write timing is revised to "ADi/DBi".
		50	Appendix 1. Package Dimensions: 100P6Q-A is added.
2.10	Jun. 24, 2005	—	Revised edition issued * The contents of product are revised. (Normal-ver. is added.) * Revised parts and revised contents are as follows (except for expressional change).
		2	Table 1.1 Performance outline of M16C/6N Group (M16C/6N4) • Performance outline of Normal-ver. is added.
		4	Table 1.2 Product List is revised. (Normal-ver. is added.) Figure 1.2 Type No., Memory Size, and Package: • "(no): Normal-ver." is added to Characteristics.
		19	Figure 4.7 SFR Information (7): NOTE 1 is revised.
		32	Table 5.4 Electrical Characteristics (1) • Measuring Condition of $V_{OL}$ is revised from " $L_{OL} = -200\mu A$ " to " $L_{OL} = 200\mu A$ ".
		33	Table 5.5 Electrical Characteristics (2): Mask ROM (5th item) • " $f(XCIN)$ " is changed to " $f(BCLK)$ ".
		34	Table 5.6 A/D Conversion Characteristics: "Tolerance Level Impedance" is deleted.
2.40	Aug. 25, 2006	—	Revised edition issued * Electric Characteristics of Normal-ver. is added. * Revised parts and revised contents are as follows (except for expressional change).
		1	1.1 Applications: Comment of Normal-ver. is added.
		4	Table 1.2 Product Information • Status of development is revised and NOTES 1 and 2 are added.

# REVISION HISTORY

# M16C/6N Group (M16C/6N4) Data Sheet

Rev.	Date	Description	
		Page	Summary
2.40	Aug. 25, 2006	7, 8 9 22 33 34 52 to 87	<p>Tables 1.3 and 1.4 List of Pin Names (1)(2) are added.</p> <p>Table 1.5 Pin Functions (1)</p> <ul style="list-style-type: none"> <li>• 3.0 to 5.5 V (Normal-ver.) is added to Description of Power supply input.</li> </ul> <p>Table 4.8 SFR Information (8)</p> <ul style="list-style-type: none"> <li>• The value of After Reset in IDB0 register is revised.</li> <li>• The value of After Reset in IDB1 register is revised.</li> </ul> <p>Table 5.3 Recommended Operating Conditions (2)</p> <ul style="list-style-type: none"> <li>• Power supply ripple is deleted. (three items)</li> </ul> <p>Figure 5.1 Voltage Fluctuation Timing is deleted.</p> <p>Table 5.4 Electrical Characteristics (1): Hysteresis XIN is deleted.</p> <p>5.2 Electrical Characteristics (Normal-ver.) is added.</p>

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